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### In the Specification

Please replace the paragraph that begins at page 7, line 20 and ends at page 9, line 9 (immediately following the heading "BRIEF DESCRIPTION OF THE FIGURES") with the following amended version of that paragraph:

Figures 1a to 1j show a dielectric and semiconductor membrane substrate in cross-section.

Figure 2 shows an etched silicon substrate membrane in cross-section.

Figures 3a, 3b show dielectric membranes with semiconductor devices.

Figure 4 shows an alignment mark of a circuit membrane in cross-section.

Figure 5 shows support structures for a membrane structure isolation structure.

Figure 6a to 6i show a circuit membrane Air Tunnel structure.

Figure 7 shows stacked circuit membranes with optical input/output.

Figure 8 shows a three dimensional circuit membrane.

Figures 9a to 9j show fabrication of a MOSFET in a membrane.

Figures 10a to 10d show fabrication of a transistor by lateral epitaxial growth on a membrane.

Figures 11a to 11f show vertical MOSFET and bipolar transistors formed on a membrane.

Figure 12a to 12g show transistor fabrication on a membrane using confined laterally doped epitaxy.

Figures 12h to 12j show cross-sections of selective epitaxial growth on a membrane.

Figures 13a to 13d show cross-sections of multi-chip modules.

Figure 14 shows a cross-section of a membrane formed on a reusable substrate.

Figure 15 shows a cross-section of the membrane of Figure 14 with a support frame attached.

Figures 16a, 16b show multi-chip nodules in packages.

Figures 17a to 17c show soldering of bond pads of a circuit membrane to a die.

Figure 18 shows bond pads on a die.

Figures 19a, 19b show bonding and de-bonding of a die to a circuit membrane.

Figures 20, 21 show two sides of a circuit membrane.

Figures 22a to 22c show formation of a metal trace in a circuit membrane by a lift-off process.

Figures 23a, 23b show use of a buried etch stop layer to form a circuit membrane having a thinner inner portion.

Figures 24, 25 show a source-integrated light valve 30 for direct write lithography.

Figures 26, 27 are cross-sections of X-ray sources for the device of Figures 24, 25.

Figures 28a to 28b show a coil for the device of Figure 24.

Figures 29a to 29k show portions of a source-external radiation valve for direct write lithography device.

Figures 29l to 29n and 29p show use of fixed freestanding membrane lithography masks.

Figure 30 shows a cross-section of a lithographic 5 tool.

Figures 31a to 31c show cross-sections of a display formed on a membrane.

Figures 32a, 32b show bonding of two circuit membranes.

Figures 32c and 32d show die cut from a circuit membrane and bonded onto a rigid substrate.